

# N-Channel 150-V (D-S) 175 °C MOSFET

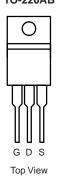
| PRODUCT SUMMARY     |                                 |                    |  |  |  |
|---------------------|---------------------------------|--------------------|--|--|--|
| V <sub>DS</sub> (V) | $R_{DS(on)}(\Omega)$            | I <sub>D</sub> (A) |  |  |  |
| 150                 | 0.030 at V <sub>GS</sub> = 10 V | 50                 |  |  |  |
| 150                 | 0.033 at V <sub>GS</sub> = 6 V  | 45                 |  |  |  |

### **FEATURES**

- TrenchFET® Power MOSFETs
- 175 °C Junction Temperature
- New Low Thermal Resistance Package
- PWM Optimized
- Compliant to RoHS Directive 2002/95/EC

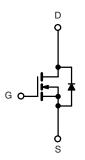


### TO-220AB



## **APPLICATIONS**

· Primary Side Switch



N-Channel MOSFET

| <b>ABSOLUTE MAXIMUM RATINGS</b> T <sub>C</sub> = 25 °C, unless otherwise noted |                                     |                                   |                  |      |  |
|--|-------------------------------------|-----------------------------------|------------------|------|--|
| Parameter  |                                     | Symbol                            | Limit            | Unit |  |
| Drain-Source Voltage   |                                     | V <sub>DS</sub>                   | 150              | V    |  |
| Gate-Source Voltage  |                                     | V <sub>GS</sub>                   | ± 20             | 7 v  |  |
| Continuous Drain Current (T <sub>.I</sub> = 175 °C)                            | T <sub>C</sub> = 25 °C              | I-                                | 50               |      |  |
| Continuous Diain Current (1j = 175 C)  | T <sub>C</sub> = 125 °C             | l <sub>D</sub>                    | 35               |      |  |
| Pulsed Drain Current   |                                     | I <sub>DM</sub>                   | 150              | _ A  |  |
| Avalanche Current  |                                     | I <sub>AR</sub>                   | 50               |      |  |
| Repetitive Avalanche Energy <sup>a</sup>                                       | L = 0.1 mH                          | E <sub>AR</sub>                   | 80               | mJ   |  |
| M  | T <sub>C</sub> = 25 °C              |                                   | 166 <sup>b</sup> | 14/  |  |
| Maximum Power Dissipation <sup>a</sup>   | T <sub>A</sub> = 25 °C <sup>c</sup> | $ P_D$ $-$                        | 3.75             | W    |  |
| Operating Junction and Storage Temperature Ra                                  | nge                                 | T <sub>J</sub> , T <sub>sta</sub> | - 55 to 175      | °C   |  |

| THERMAL RESISTANCE RATINGS       |                   |       |       |  |
|----------------------------------|-------------------|-------|-------|--|
| Parameter                        | Symbol            | Limit | Unit  |  |
| Junction-to-Ambient <sup>c</sup> | R <sub>thJA</sub> | 40    | °C/W  |  |
| Junction-to-Case (Drain)         | R <sub>thJC</sub> | 0.9   | 0/ ** |  |

## Notes:

- a. Duty cycle  $\leq$  1 %.
- b. See SOA curve for voltage derating.
- c. When Mounted on 1" square PCB (FR-4 material).

服务热线:400-655-8788

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| <b>SPECIFICATIONS</b> T <sub>J</sub> = 25 °C, unless otherwise noted     |                      |   |      |       |       |              |  |
|--|----------------------|---|------|-------|-------|--------------|--|
| Parameter  | Symbol               | Test Conditions   | Min. | Тур.  | Max.  | Unit         |  |
| Static   |                      |   |      |       |       |              |  |
| Drain-Source Breakdown Voltage   | $V_{DS}$             | $V_{DS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$                         | 150  |       |       | V            |  |
| Gate-Threshold Voltage   | V <sub>GS(th)</sub>  | $V_{DS} = V_{GS}, I_{D} = 250 \mu A$                                    | 2    |       | 4     | V            |  |
| Gate-Body Leakage  | I <sub>GSS</sub>     | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$                       |      |       | ± 100 | nA           |  |
|  |                      | V <sub>DS</sub> = 120 V, V <sub>GS</sub> = 0 V                          |      |       | 1     |              |  |
| Zero Gate Voltage Drain Current  | I <sub>DSS</sub>     | V <sub>DS</sub> = 120 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C |      |       | 50    | 50 μA<br>250 |  |
|  |                      | V <sub>DS</sub> = 120 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 175 °C |      |       | 250   |              |  |
| On-State Drain Current <sup>a</sup>                                      | I <sub>D(on)</sub>   | $V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$                         | 80   |       |       | Α            |  |
|  |                      | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 15 A                           |      | 0.030 |       |              |  |
| Due to Course On Otata Destatore a                                       | В                    | V <sub>GS</sub> = 6 V, I <sub>D</sub> = 10 A                            |      | 0.033 |       | 1            |  |
| Drain-Source On-State Resistance <sup>a</sup>                            | R <sub>DS(on)</sub>  | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 15 A, T <sub>J</sub> = 125 °C  |      | 0.076 |       | Ω            |  |
|  |                      | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 15 A, T <sub>J</sub> = 175 °C  |      | 0.100 |       |              |  |
| Forward Transconductance <sup>a</sup>                                    | 9 <sub>fs</sub>      | V <sub>DS</sub> = 15 V, I <sub>D</sub> = 15 A                           | 10   |       |       | S            |  |
| Dynamic <sup>b</sup>   | •                    |   |      | •     |       |              |  |
| Input Capacitance  | C <sub>iss</sub>     |   |      | 2500  |       | pF           |  |
| Output Capacitance   | C <sub>oss</sub>     | $V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$        |      | 290   |       |              |  |
| Reverse Transfer Capacitance   | C <sub>rss</sub>     |   |      | 190   |       |              |  |
| Gate Resistance  | $R_{g}$              |   |      | 2     |       | Ω            |  |
| Total Gate Charge <sup>c</sup>   | $Q_g$                |   |      | 38    | 60    |              |  |
| Gate-Source Charge <sup>c</sup>  | $Q_{gs}$             | $V_{DS} = 75 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 40 \text{ A}$    |      | 13    |       | nC           |  |
| Gate-Drain Charge <sup>c</sup>   | $Q_{gd}$             |   |      | 13    |       |              |  |
| Turn-On Delay Time <sup>c</sup>  | t <sub>d(on)</sub>   |   |      | 15    | 25    |              |  |
| Rise Time <sup>c</sup>   | t <sub>r</sub>       | $V_{DD} = 75 \text{ V}, R_{L} = 1.80 \Omega$                            |      | 130   | 200   | ns           |  |
| Turn-Off Delay Time <sup>c</sup>   | t <sub>d(off)</sub>  | $I_D \cong 40 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 2.5 \Omega$      |      | 30    | 45    |              |  |
| Fall Time <sup>c</sup>   | t <sub>f</sub>       |   |      | 90    | 140   |              |  |
| Source-Drain Diode Ratings and Characteristics $T_C = 25  {}^{\circ}C^b$ |                      |   |      |       |       |              |  |
| Continuous Current   | I <sub>S</sub>       |   |      |       | 40    |              |  |
| Pulsed Current   | I <sub>SM</sub>      |   |      |       | 80    | A            |  |
| Forward Voltage <sup>a</sup>   | V <sub>SD</sub>      | I <sub>F</sub> = 40 A, V <sub>GS</sub> = 0 V                            |      | 1.0   | 1.5   | V            |  |
| Reverse Recovery Time  | t <sub>rr</sub>      |   |      | 100   | 150   | ns           |  |
| Peak Reverse Recovery Current  | I <sub>RM(REC)</sub> | I <sub>F</sub> = 40 A, dl/dt = 100 A/μs                                 |      | 5     | 8     | Α            |  |
| Reverse Recovery Charge  | Q <sub>rr</sub>      |   |      | 0.25  | 0.6   | μC           |  |

### Notes:

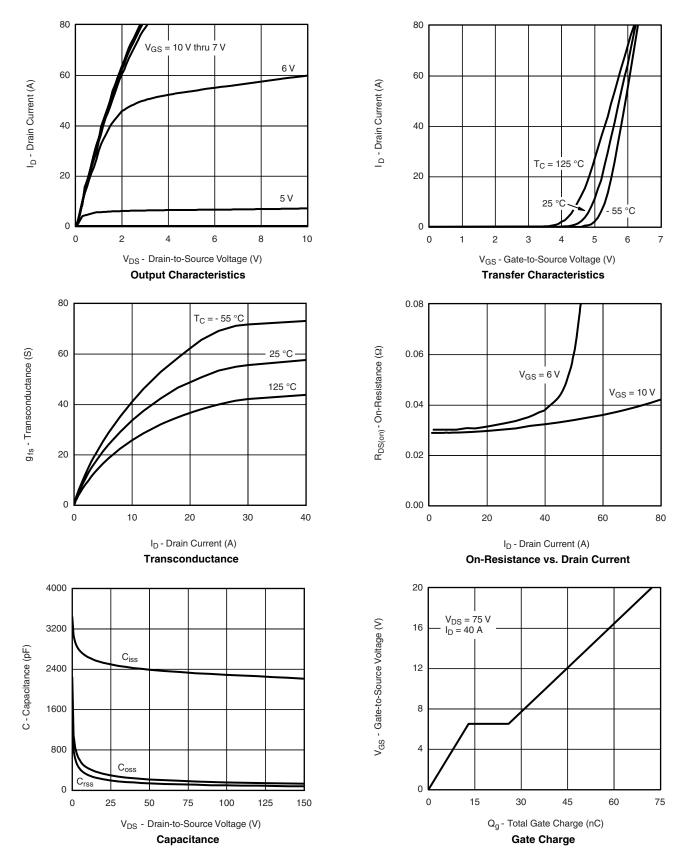
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- a. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 % b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



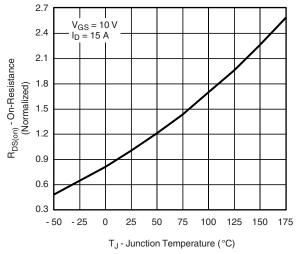
## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

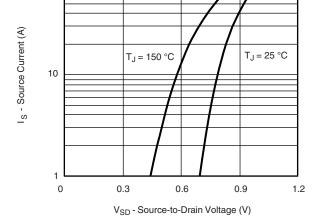


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## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

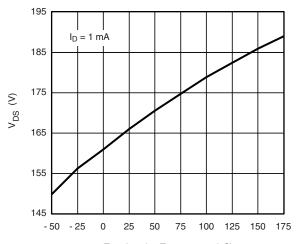




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On-Resistance vs. Junction Temperature

Source-Drain Diode Forward Voltage

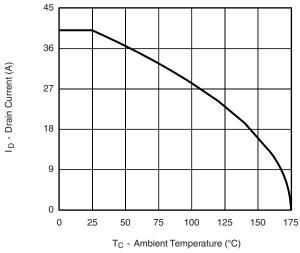


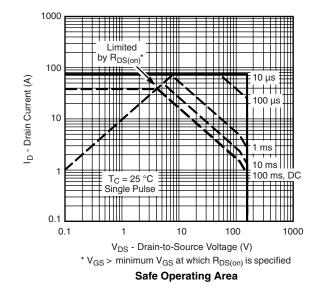
 $T_J$  - Junction Temperature (°C)

Drain Source Breakdown vs. Junction Temperature

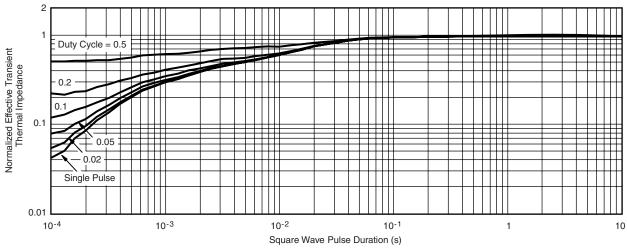


### THERMAL RATINGS





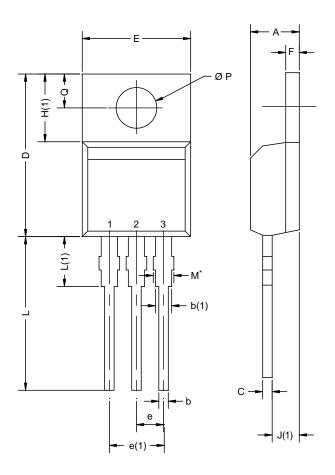
Maximum Avalanche and Drain Current vs. Case Temperature



Normalized Thermal Transient Impedance, Junction-to-Case



## **TO-220AB**



|                                 | MILLIM | IETERS | INC   | HES   |  |
|---------------------------------|--------|--------|-------|-------|--|
| DIM.                            | MIN.   | MAX.   | MIN.  | MAX.  |  |
| Α                               | 4.25   | 4.65   | 0.167 | 0.183 |  |
| b                               | 0.69   | 1.01   | 0.027 | 0.040 |  |
| b(1)                            | 1.20   | 1.73   | 0.047 | 0.068 |  |
| С                               | 0.36   | 0.61   | 0.014 | 0.024 |  |
| D                               | 14.85  | 15.49  | 0.585 | 0.610 |  |
| Е                               | 10.04  | 10.51  | 0.395 | 0.414 |  |
| е                               | 2.41   | 2.67   | 0.095 | 0.105 |  |
| e(1)                            | 4.88   | 5.28   | 0.192 | 0.208 |  |
| F                               | 1.14   | 1.40   | 0.045 | 0.055 |  |
| H(1)                            | 6.09   | 6.48   | 0.240 | 0.255 |  |
| J(1)                            | 2.41   | 2.92   | 0.095 | 0.115 |  |
| L                               | 13.35  | 14.02  | 0.526 | 0.552 |  |
| L(1)                            | 3.32   | 3.82   | 0.131 | 0.150 |  |
| ØΡ                              | 3.54   | 3.94   | 0.139 | 0.155 |  |
| Q                               | 2.60   | 3.00   | 0.102 | 0.118 |  |
| ECN: X12-0208-Rev. N, 08-Oct-12 |        |        |       |       |  |

ECN: X12-0208-Rev. N, 08-Oct-12 DWG: 5471

## Notes

 $<sup>^{\</sup>star}$  M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM



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DMN2080UCB4-7 DMN61D9UWQ-13 US6M2GTR DMN31D5UDJ-7 DMP22D4UFO-7B DMN1006UCA6-7 DMN16M9UCA6-7
STF5N65M6 IRF40H233XTMA1 STU5N65M6 DMN6022SSD-13 DMN13M9UCA6-7 DMTH10H4M6SPS-13 DMN2990UFB-7B
IPB80P04P405ATMA2 2N7002W-G MCAC30N06Y-TP MCQ7328-TP NTMC083NP10M5L NVMFS2D3P04M8LT1G BXP7N65D
BXP4N65F AOL1454G WMJ80N60C4 BXP2N20L BXP2N65D BXT1150N10J BXT1700P06M TSM60NB380CP ROG RQ7L055BGTCR
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